

Fig. 1  
(Prior Art)

✓ 200

Deposit metal film on a  
substrate.

-205

Deposit photo resist on the  
metal film and pattern Photo-  
resist to expose undesired  
portions of the metal film.

-210

Use a chelating agent  
to remove the undesired  
portion of the metal film.

-215

Fig. 2

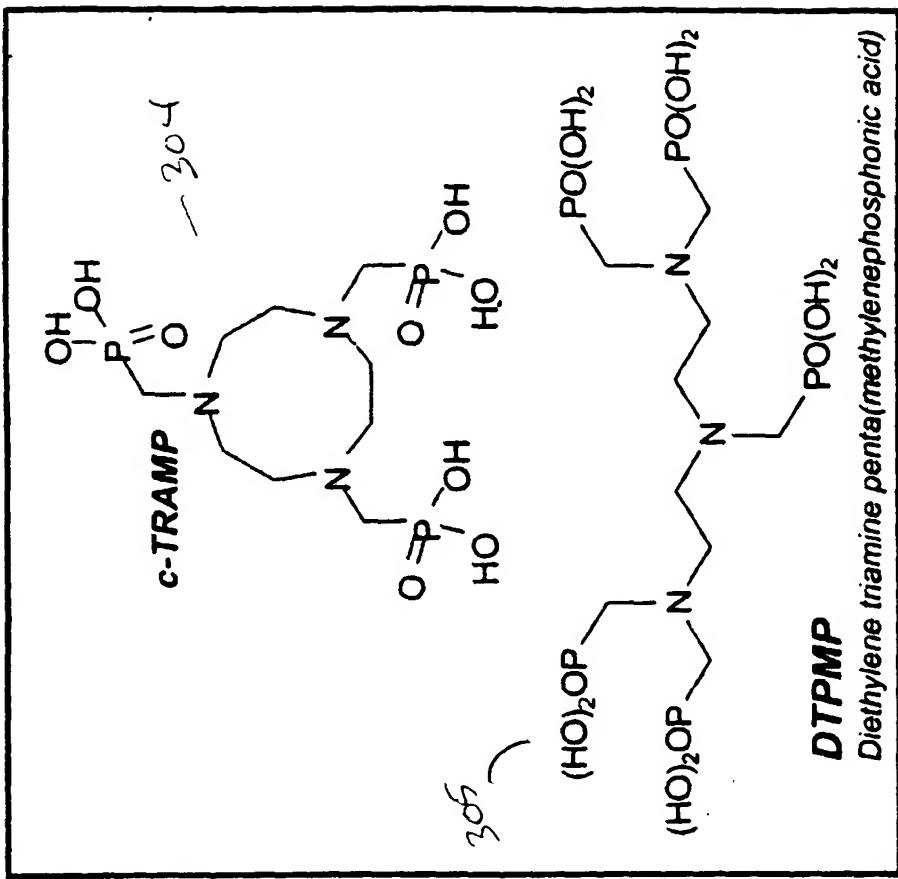


Fig. 3C

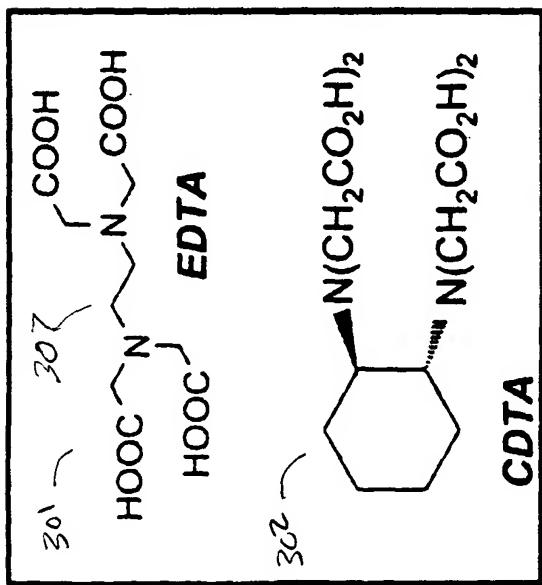
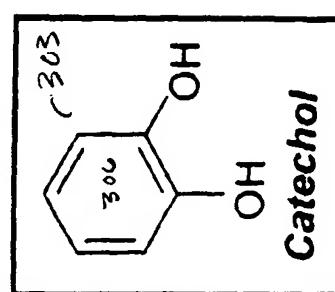


Fig. 3A



**Phenol derivatives**

Fig. 3B

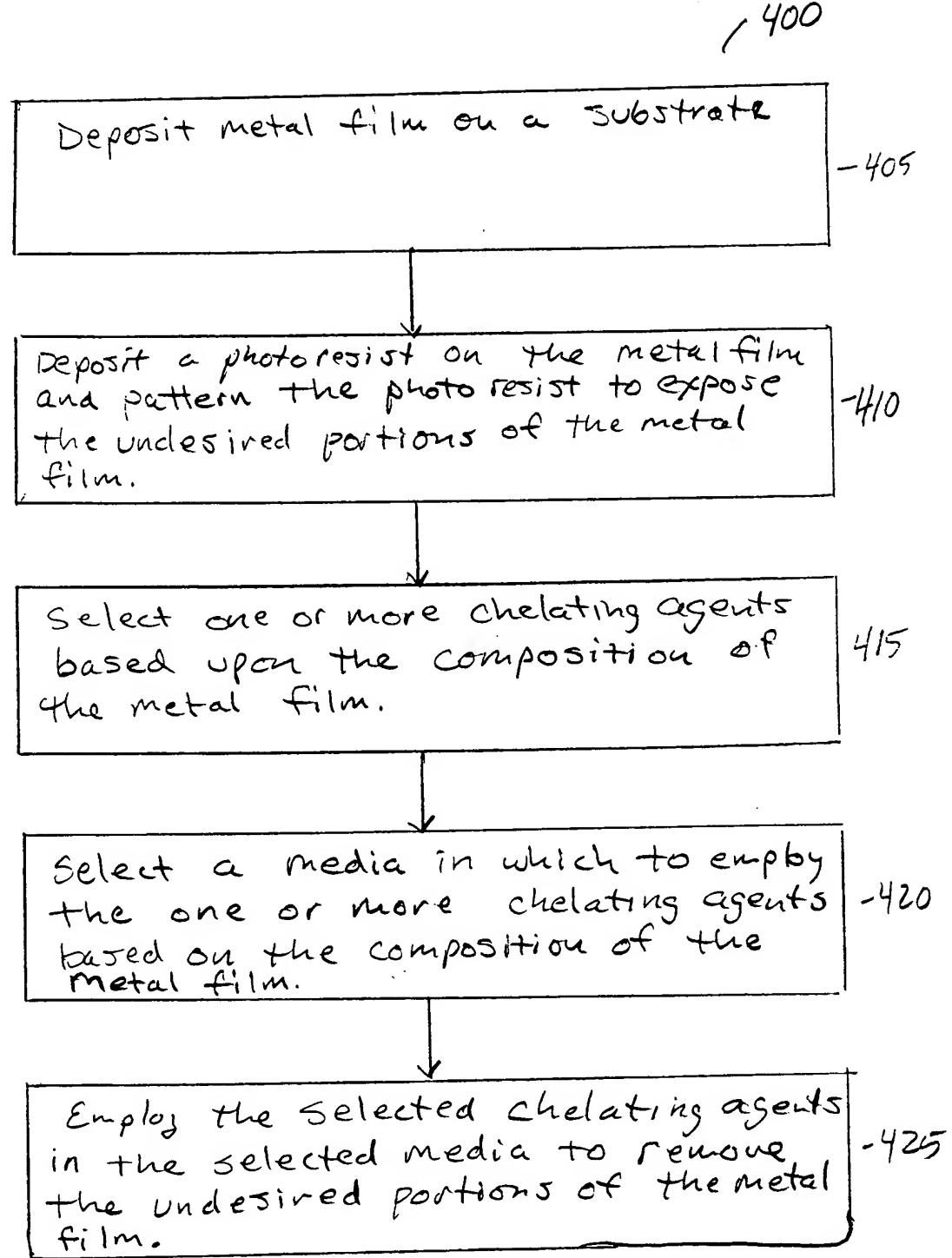


Fig. 21